

General Description

The A07411 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 1.8V. This device is suitable for use as a load switch or in PWM applications. *Standard Product A07411 is Pb-free (meets ROHS & Sony 259 specifications). A07411L is a Green Product ordering option. A07411 and A07411L are electrically identical.*

Features

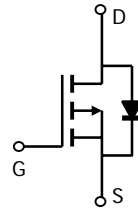
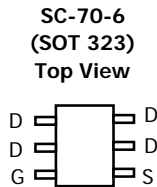
$$V_{DS} (V) = -20V$$

$$I_D = -1.8 A (V_{GS} = -4.5V)$$

$$R_{DS(ON)} < 120m\Omega (V_{GS} = -4.5V)$$

$$R_{DS(ON)} < 150m\Omega (V_{GS} = -2.5V)$$

$$R_{DS(ON)} < 200m\Omega (V_{GS} = -1.8V)$$



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 8	V
Continuous Drain Current ^A	I_D	-1.8	A
		-1.5	
Pulsed Drain Current ^B	I_{DM}	-10	
Power Dissipation ^A	P_D	0.625	W
		0.4	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	160	200	$^\circ C/W$
		180	220	
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	130	160	$^\circ C/W$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =-250μA, V _{GS} =0V	-20			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-16V, V _{GS} =0V T _J =55°C			-1 -5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±8V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} I _D =-250μA	-0.4	-0.55	-0.8	V
I _{D(ON)}	On state drain current	V _{GS} =-4.5V, V _{DS} =-5V	-10			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-4.5V, I _D =-1.8A T _J =125°C		95 129	120 160	mΩ
		V _{GS} =-2.5V, I _D =-1.6A		121	150	mΩ
		V _{GS} =-1.8V, I _D =-1.0A		155	200	mΩ
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-1.8A	4	7		S
V _{SD}	Diode Forward Voltage	I _S =-1A, V _{GS} =0V		-0.83	-1	V
I _S	Maximum Body-Diode Continuous Current				-0.6	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-10V, f=1MHz		524		pF
C _{oss}	Output Capacitance			93		pF
C _{rss}	Reverse Transfer Capacitance			73		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		12		Ω
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =-4.5V, V _{DS} =-10V, I _D =-1.8A		6.24		nC
Q _{gs}	Gate Source Charge			0.52		nC
Q _{gd}	Gate Drain Charge			1.84		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =-4.5V, V _{DS} =-10V, R _L =5.6Ω, R _{GEN} =3Ω		10.5		ns
t _r	Turn-On Rise Time			11.8		ns
t _{D(off)}	Turn-Off DelayTime			54.5		ns
t _f	Turn-Off Fall Time			24.7		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =-1.8A, dI/dt=100A/μs		24.7		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =-1.8A, dI/dt=100A/μs		8.2		nC

A: The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t_s ≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

D: The static characteristics in Figures 1 to 6,12,14 are obtained using 80μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

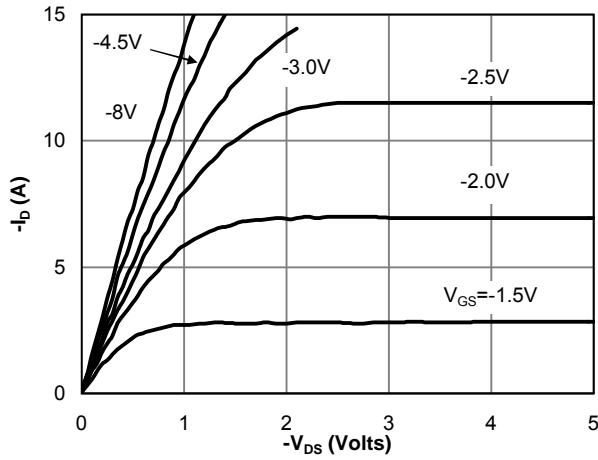


Fig 1: On-Region Characteristics

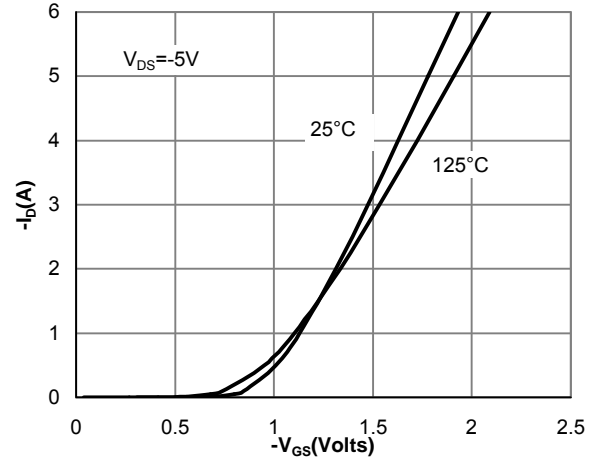


Figure 2: Transfer Characteristics

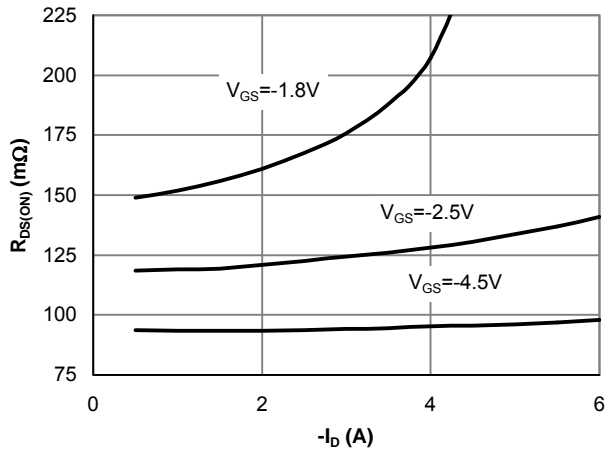


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

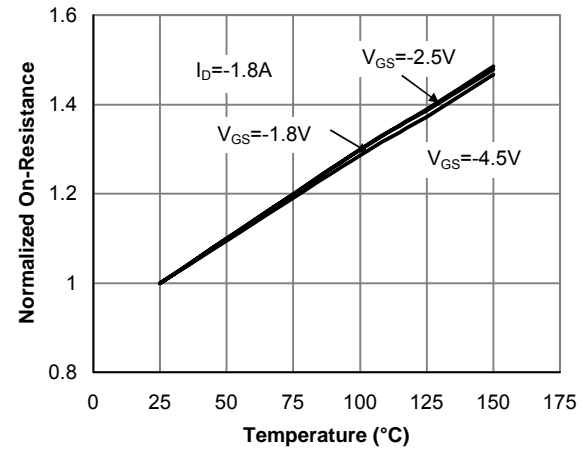


Figure 4: On-Resistance vs. Junction Temperature

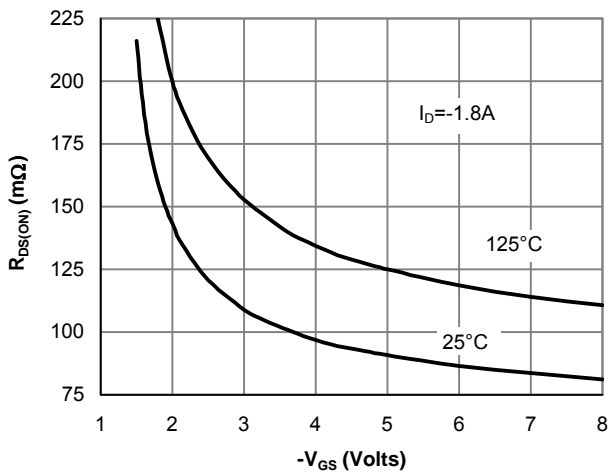


Figure 5: On-Resistance vs. Gate-Source Voltage

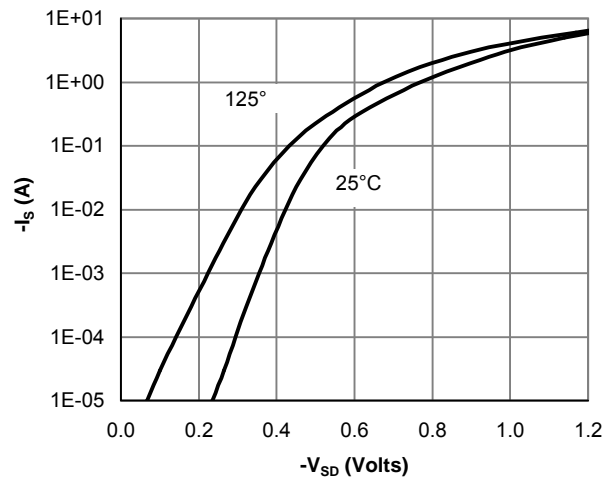


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

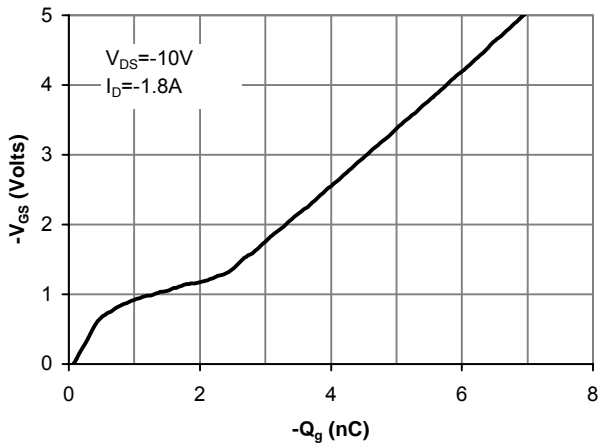


Figure 7: Gate-Charge Characteristics

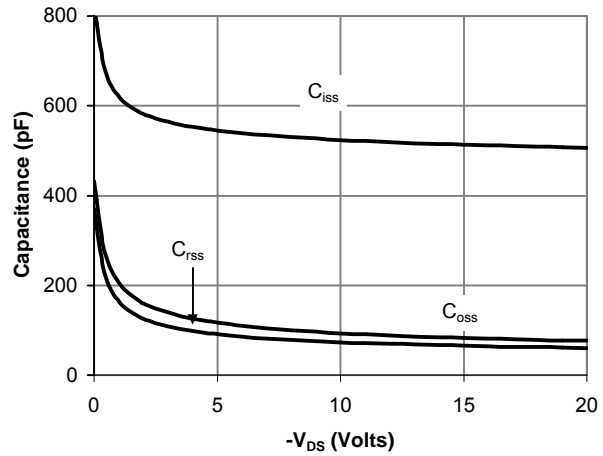


Figure 8: Capacitance Characteristics

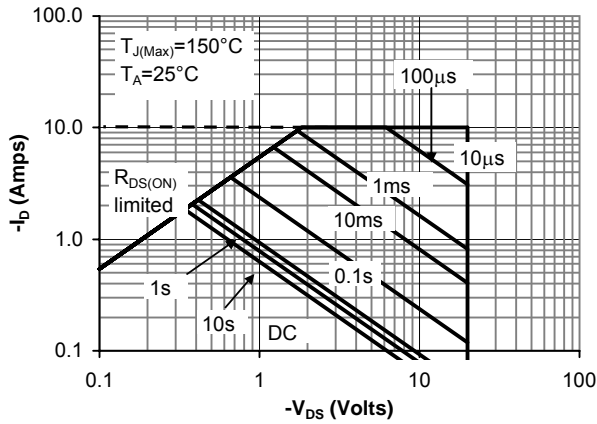


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

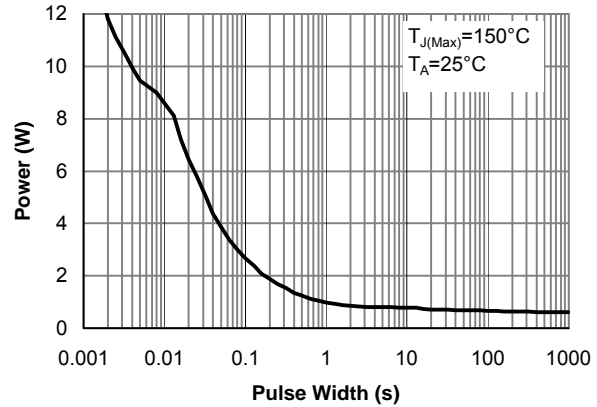


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

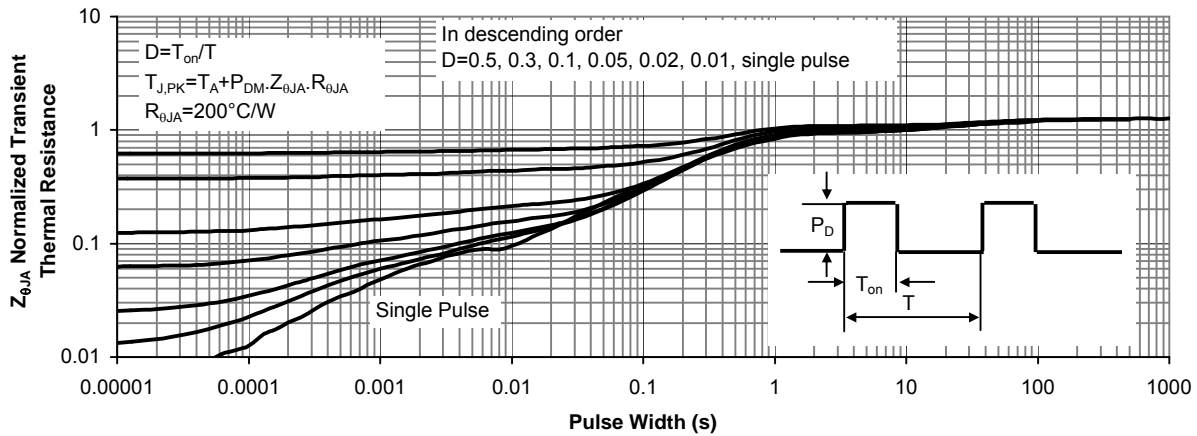


Figure 11: Normalized Maximum Transient Thermal Impedance